

Surface Mount Fuse with Clip, 11.1 x 3.8 mm, Time-Lag T, UMZ 250 = UMT 250 (Au) + UMC 250

new



IEC 60127-4 · 250VAC · 125VDC · Time-Lag T

**Description**

- Explanation VDE/UL Approvals UMT 250, UMT 250 (Au), UMC 250 , see variants
- High breaking capacity of 200 A @ 250 VAC (IEC)
- UL approval for 277 VAC and 250 VDC

Standards

- IEC 60127-4/2
- UL 248-14
- CSA C22.2 no. 248.14

Approvals

- VDE License Number: 40013121
- UL File Number: E39328

Applications

- Primary Protection on SMD PCB
- Industrial electronic


References

[General Product Information](#)
[Packaging Details](#)

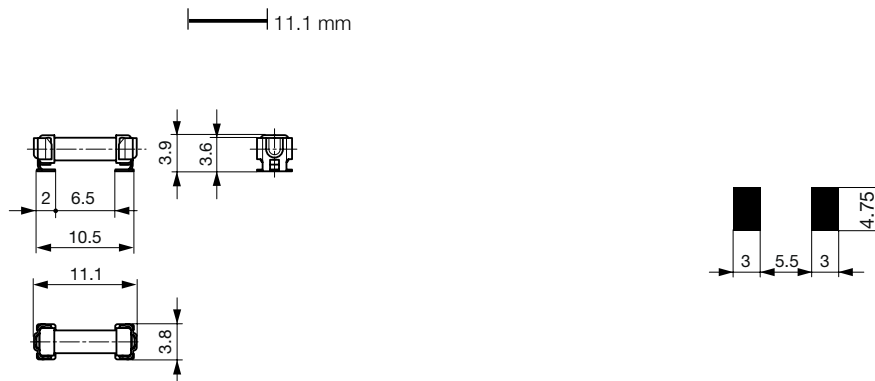
Weblinks

[Approvals](#), [RoHS](#), [CHINA-RoHS](#), [SCHURTER-Stock-Check](#), [Distributor-Stock-Check](#)

Technical Data

Rated Voltage	250VAC, 125VDC
Rated Current	0.08 - 4A
Breaking Capacity	200A
Characteristic	Time-Lag T
Mounting	PCB,SMT
Admissible Ambient Air Temp.	-40°C to 85°C
Climatic Category	40/085/21 acc. to IEC 60068-1
Material: Housing	Ceramic
Material: Terminals	Gold-Plated Copper Alloy
Storage Conditions	0°C to 60°C, max. 70% r.h.
Product Marking	 Current, Voltage, Characteristic, Breaking Capacity

Soldering Methods	Reflow
Solderability	245°C / 3sec acc. to IEC 60068-2-58, Test Td
Resistance to Soldering Heat	260°C / 40sec acc. to IPC/JEDEC J-STD-020D, 1 cycle
Life Test	MIL-STD-202, Method 108A (1000h @ 0.42*In @ 70°C)
Moisture Resistance Test	MIL-STD-202, Method 106E (50 cycles in a temp./mister chamber)
Terminal Strength	MIL-STD-202, Method 211A (Deflection of board 1 mm for 1 minute)
Mechanical Shock	MIL-STD-202, Method 213B (Shock 50gn, half sine wave, 11 ms)
Resistance to Solvents	MIL-STD-202, Method 215A
Flammability	min. UL 94V-1 (acc. to EIA/IS-722, Test 4.12)

Dimensions

Soldering pads

Pre-Arcing Time

Rated Current In	1.25 x In min.	2.0 x In max.	10.0 x In min.	10.0 x In max.
0.08 A - 4.0 A	60 min	120 s	10 ms	100 ms

Variants

Rated Current [A]	Rated Voltage [VAC]	Rated Voltage [VDC]	Breaking Capacity	Voltage Drop 1.0 In max. [mV]	Voltage Drop 1.0 In typ. [mV]	Power Dissipation 1.25 In max [mW]	Melting I ² t 10.0 Intyp. [A ² s]	Order Number
0.08	250	125	1)	-	1030	-	0.022	3404.2405.xx
0.1	250	125	1)	1300	850	200	0.04	3404.2406.xx
0.125	250	125	1)	1000	700	200	0.055	3404.2407.xx
0.16	250	125	1)	1000	540	240	0.057	3404.2408.xx
0.2	250	125	1)	1000	460	500	0.092	3404.2409.xx
0.25	250	125	1)	800	395	500	0.2	3404.2410.xx
0.315	250	125	1)	750	344	500	0.27	3404.2411.xx
0.4	250	125	1)	700	320	500	0.4	3404.2412.xx
0.5	250	125	1)	600	264	500	0.54	3404.2413.xx
0.63	250	125	1)	500	216	500	1.1	3404.2414.xx
0.8	250	125	1)	400	174	500	1.4	3404.2415.xx
1	250	125	1)	300	174	500	2.8	3404.2416.xx
1.25	250	125	1)	300	140	1000	4.5	3404.2417.xx
1.6	250	125	1)	300	130	1000	6.9	3404.2418.xx
2	250	125	1)	300	103	1000	7.3	3404.2419.xx
2.5	250	125	1)	300	90	1200	7.5	3404.2420.xx
3.15	250	125	1)	300	95	1500	14	3404.2421.xx
4	250	125	1)	300	83	2000	26	3404.2422.xx

1) IEC: 200 A @ 250 VAC, p.f. ≥ 0.95 / 100 A @ 125 VDC

1) UL: 200 A @ 277 VAC / 100 A @ 125 VDC / 35 A @ 250 VDC / 200 A @ 63 VAC/DC

Approval Overview

UMT 250 -> Fuse with tin-plated caps, Approval Status: VDE, UL LISTED, cURus, Free of CCC, PSE JET, KTL

UMT 250 (Au) -> Fuse with gold-plated caps, Approval Status: VDE Mark and cURus

UMC 250 -> Clip, Approval Status: VDE UG Mark and cURus

UMZ 250 = UMT 250 (Au) + UMC 250

There is no approval existing for the combination fuse and clip UMZ 250, but the fuse and the clip are fully approved independently at VDE/UL. See details above.

In the reflow soldering process, the fuse must have gold-plated caps, otherwise fuse and clip would be soldered together. For fuse replacement in the field, a standard UMT 250 fuse with tin-plated caps can be used.

Packaging Unit

.xx = .11 Plastic Bag (100 pcs.)

.xx = .22 Blister Tape 33 cm Reel (1000 pcs.)

Time-Current-Curves

